COM'L: H-5/7/10/15/25, Q-10/15/25 IND: H-15/25, Q-20/25

MIL: H-15/20/25

Advanced Devices

PALCE20V8 Family

EE CMOS 24-Pin Universal Programmable Array Logic

DISTINCTIVE CHARACTERISTICS

- Pin, function and fuse-map compatible with all GAL 20V8/As
- Electrically erasable CMOS technology provides reconfigurable logic and full testability
- High-speed CMOS technology
 - 5 ns propagation delay for "-5" version
 - 7.5 ns propagation delay for "-7" version
- Direct plug-in replacement for a wide range of 24-pin PAL devices
- Programmable enable/disable control
- Outputs individually programmable as registered or combinatorial

- Preloadable output registers for testability
- Automatic register reset on power-up
- Cost-effective 24-pin plastic SKINNYDIP and 28-pin PLCC packages
- Extensive third-party software and programmer support through FusionPLD partners
- Fully tested for 100% programming and functional yields and high reliability
- Programmable output polarity
- 5 ns version utilizes a split leadframe for improved performance

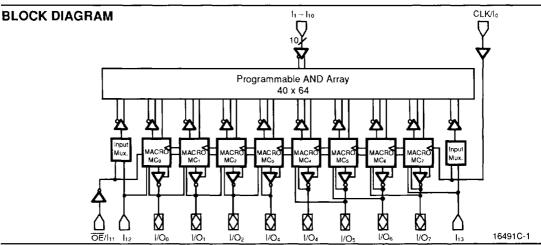
GENERAL DESCRIPTION

The PALCE20V8 is an advanced PAL device built with low-power, high-speed, electrically-erasable CMOS technology. Its macrocells provide a universal device architecture. The PALCE20V8 is fully compatible with the GAL20V8 and can directly replace PAL20R8 series devices and most 24-pin combinatorial PAL devices.

Device logic is automatically configured according to the user's design specification. A design is implemented using any of a number of popular design software packages, allowing automatic creation of a programming file based on Boolean or state equations. Design software also verifies the design and can provide test vectors for the finished device. Programming can be accomplished on standard PAL device programmers.

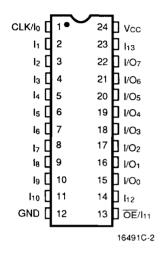
The PALCE20V8 utilizes the familiar sum-of-products (AND/OR) architecture that allows users to implement complex logic functions easily and efficiently. Multiple levels of combinatorial logic can always be reduced to sum-of-products form, taking advantage of the very wide input gates available in PAL devices. The equations are programmed into the device through floatinggate cells in the AND logic array that can be erased electrically.

The fixed OR array allows up to eight data product terms per output for logic functions. The sum of these products feeds the output macrocell. Each macrocell can be programmed as registered or combinatorial with an active-high or active-low output. The output configuration is determined by two global bits and one local bit controlling four multiplexers in each macrocell.

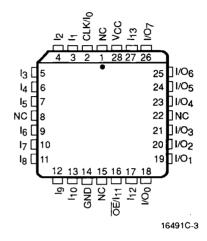


CONNECTION DIAGRAMS (Top View)

SKINNYDIP



PLCC/LCC



Note:

Pin 1 is marked for orientation.

PIN DESIGNATIONS

CLK = Clock

GND = Ground

I = Input

I/O = Input/Output

NC = No Connect

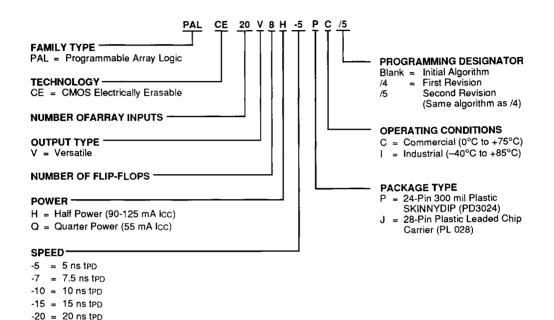
OE = Output Enable

Vcc = Supply Voltage

ORDERING INFORMATION

Commercial and Industrial Products

AMD programmable logic products for commercial and industrial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of:



Valid Combinations						
PALCE20V8H-5	JC					
PALCE20V8H-7		/5				
PALCE20V8H-10	PC, JC	Blank, /4				
PALCE20V8Q-10		/5				
PALCE20V8H-15	PC, JC, PI, JI					
PALCE20V8Q-15	PC, JC	Blank,				
PALCE20V8Q-20	PI, JI	/4				
PALCE20V8H-25	BO 10 BI II					
PALCE20V8Q-25	PC, JC, PI, JI					

-25 = 25 ns tpp

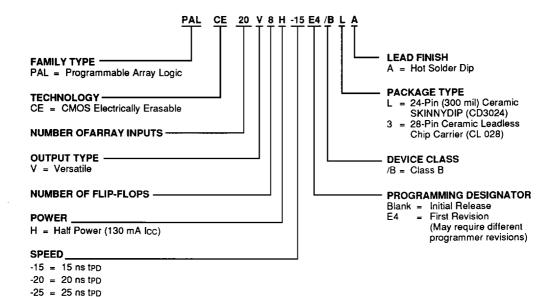
Valid Combinations

Valid Combinations lists configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

ORDERING INFORMATION

APL Products

AMD programmable logic products for Aerospace and Defense applications are available with several ordering options. APL (Approved Products List) products are fully compliant with MIL-STD-883 requirements. The order number (Valid Combination) is formed by a combination of:



Valid Combinations					
PALCE20V8H-15	E4				
PALCE20V8H-20	Blank,	/BLA, /B3A			
PALCE20V8H-25 E4					

Valid Combinations

Valid Combinations lists configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

Group A Tests

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

Military Burn-In

Military burn-in is in accordance with the current revision of MIL-STD-883, Test Method 1015, Conditions A through E. Test conditions are selected at AMD's option.



FUNCTIONAL DESCRIPTION

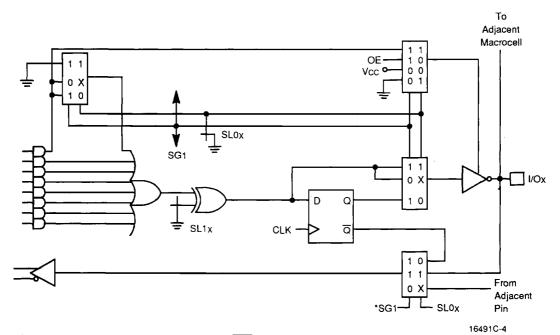
The PALCE20V8 is a universal PAL device. It has eight independently configurable macrocells (MC₀..MC₇). Each macrocell can be configured as a registered output, combinatorial output, combinatorial I/O, or dedicated input. The programming matrix implements a programmable AND logic array, which drives a fixed OR logic array. Buffers for device inputs have complementary outputs to provide user-programmable input signal polarity. Pins 1 and 13 serve either as array inputs or as clock (CLK) and output enable (OE) for all flip-flops.

Unused input pins should be tied directly to Vcc or GND. Product terms with all bits unprogrammed (disconnected) assume the logical HIGH state and product terms with both true and complement of any input signal connected assume a logical LOW state.

The programmable functions on the PALCE20V8 are automatically configured from the user's design specification, which can be in a number of formats. The design

specification is processed by development software to verify the design and create a programming file. This file, once downloaded to a programmer, configures the device according to the user's desired function.

The user is given two design options with the PALCE20V8. First, it can be programmed as an emulated PAL device. This includes the PAL20R8 series and most 24-pin combinatorial PAL devices. The PAL device programmer manufacturer will supply device codes for the standard PAL architectures to be used with the PALCE20V8. The programmer will program the PALCE20V8 to the corresponding PAL device architecture. This allows the user to use existing standard PAL device JEDEC files without making any changes to them. Alternatively, the device can be programmed directly as a PALCE20V8. Here the user must use the PALCE20V8 device code. This option provides full utilization of the macrocells, allowing non-standard architectures to be built.



* In Macrocells MCo and MC7, SG1 is replaced by \$\overline{SG0}\$ on the feedback multiplexer.

Figure 1. PALCE20V8 Macrocell

Configuration Options

Each macrocell can be configured as one of the following: registered output, combinatorial output, combinatorial I/O or dedicated input. In the registered output configuration, the output buffer is enabled by the OE pin. In the combinatorial configuration, the buffer is either controlled by a product term or always enabled. In the dedicated input configuration, the buffer is always disabled. A macrocell configured as a dedicated input derives the input signal from an adjacent I/O.

The macrocell configurations are controlled by the configuration control word. It contains 2 global bits (SG0 and SG1) and 16 local bits (SL00 through SL07 and SL10 through SL17). SG0 determines whether registers will be allowed. SG1 determines whether the PALCE20V8 will emulate a PAL20R8 family or a combinatorial device. Within each macrocell, SL0x, in conjunction with SG1, selects the configuration of the macrocell and SL1x sets the output as either active low or active high.

The configuration bits work by acting as control inputs for the multiplexers in the macrocell. There are four multiplexers: a product term input, an enable select, an output select, and a feedback select multiplexer. SG1 and SL0x are the control signals for all four multiplexers. In MCo and MC7, $\overline{\text{SG0}}$ replaces SG1 on the feedback multiplexer.

These configurations are summarized in table 1 and illustrated in figure 2.

If the PALCE20V8 is configured as a combinatorial device, the CLK and \overline{OE} pins may be available as inputs to the array. If the device is configured with registers, the CLK and \overline{OE} pins cannot be used as data inputs.

Registered Output Configuration

The control bit settings are SG0 = 0, SG1 = 1 and SL0x = 0. There is only one registered configuration. All eight product terms are available as inputs to the OR gate. Data polarity is determined by SL1x. SL1x is an input to the exclusive-OR gate which is the D input to the flipflop. SL1x is programmed as 1 for inverted output or 0 for non-inverted output. The flip-flop is loaded on the LOW-to-HIGH transition of CLK. The feedback path is from \overline{Q} on the register. The output buffer is enabled by \overline{QE} .

Combinatorial Configurations

The PALCE20V8 has three combinatorial output configurations: dedicated output in a non-registered device, I/O in a non-registered device and I/O in a registered device.

Dedicated Output in a Non-Registered Device

The control settings are SG0 = 1, SG1 = 0, and SL0x = 0. All eight product terms are available to the OR gate. Although the macrocell is a dedicated output, the feedback is used, with the exception of pins 18(21) and 19(23). Pins 18(21) and 19(23) do not use feedback in this mode.

Dedicated Input in a Non-Registered Device

The control bit settings are SG0 = 1, SG1 = 0 and SL0x = 1. The output buffer is disabled. The feedback signal is an adjacent I/O pin.

Combinatorial I/O in a Non-Registered Device

The control settings are SG0 = 1, SG1 = 1, and SL0x = 1. Only seven product terms are available to the OR gate. The eighth product term is used to enable the output buffer. The signal at the I/O pin is fed back to the AND array via the feedback multiplexer. This allows the pin to be used as an input.

Combinatorial I/O in a Registered Device

The control bit settings are SG0=0, SG1=1 and SL0x=1. Only seven product terms are available to the OR gate. The eighth product term is used as the output enable. The feedback signal is the corresponding I/O signal.

Table 1. Macrocell Configurations

SG0	SG1	SL0x	Cell Configuration	Devices Emulated			
	Device has registers						
0	1	0	Registered	PAL20R8, 20R6,			
			Output	20R4			
0	1	1	Combinatorial I/O	PAL20R6, 20R4			
		1	Device has no regis	ters			
1	0	0	Combinatorial	PAL20L2,			
			Output	18L4,16L6,14L8			
1	0	1	Dedicated Input	PAL20L2,18L4,			
				16L6			
1	1	1	Combinatorial I/O	PAL20L8			

Programmable Output Polarity

The polarity of each macrocell output can be active high or active low, either to match output signal needs or to reduce product terms. Programmable polarity allows Boolean expressions to be written in their most compact form (true or inverted), and the output can still be of the desired polarity. It can also save "DeMorganizing" efforts.

Selection is made through a programmable bit SL1x which controls an exclusive-OR gate at the output of the AND/OR logic. The output is active high if SL1x is a 0 and active low if SL1x is a 1.

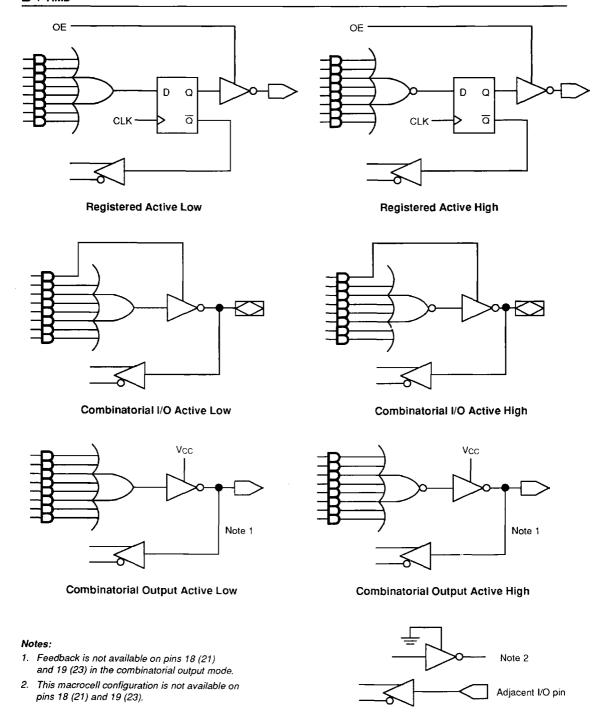


Figure 2. Macrocell Configurations

Power-Up Reset

All flip-flops power up to a logic LOW for predictable system initialization. Outputs of the PALCE20V8 depend on whether they are selected as registered or combinatorial. If registered is selected, the output will be HIGH. If combinatorial is selected, the output will be a function of the logic.

Register Preload

The register on the PALCE20V8 can be preloaded from the output pins to facilitate functional testing of complex state machine designs. This feature allows direct loading of arbitrary states, making it unnecessary to cycle through long test vector sequences to reach a desired state. In addition, transitions from illegal states can be verified by loading illegal states and observing proper recovery.

Security Bit

A security bit is provided on the PALCE20V8 as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback and verification of the programmed pattern by a device programmer, securing proprietary designs from competitors. The bit can only be erased in conjunction with the array during an erase cycle.

Electronic Signature Word

An electronic signature word is provided in the PALCE20V8. It consists of 64 bits of programmable memory that can contain any user-defined data. The signature data is always available to the user independent of the security bit.

Programming and Erasing

The PALCE20V8 can be programmed on standard logic programmers. It also may be erased to reset a previously configured device back to its virgin state. Erasure is automatically performed by the programming hardware. No special erase operation is required.

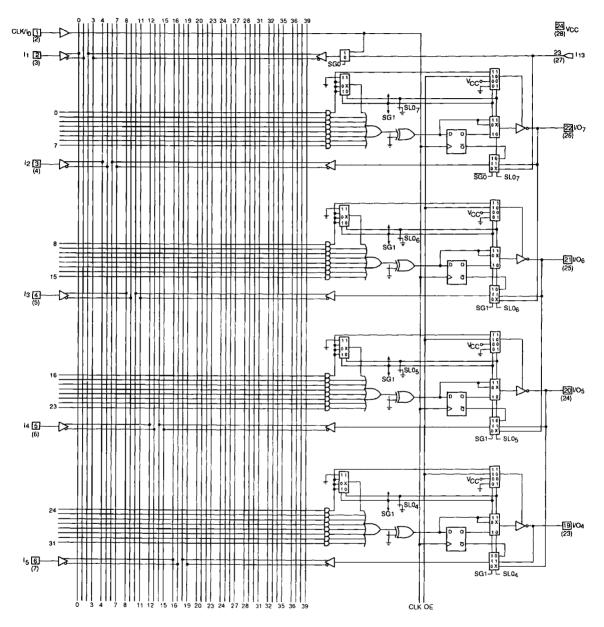
Quality and Testability

The PALCE20V8 offers a very high level of built-in quality. The erasability of the device provides a direct means of verifying performance of all AC and DC parameters. In addition, this verifies complete programmability and functionality of the device to provide the highest programming and post-programming functional yields in the industry.

Technology

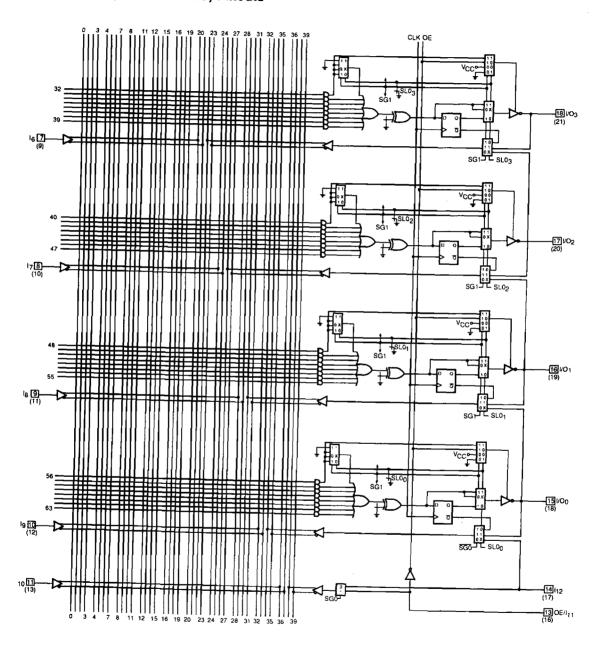
The high-speed PALCE20V8H is fabricated with AMD's advanced electrically erasable (EE) CMOS process. The array connections are formed with proven EE cells. Inputs and outputs are designed to be compatible with TTL devices. This technology provides strong input clamp diodes, output slew-rate control, and a grounded substrate for clean switching.

LOGIC DIAGRAM SKINNYDIP (PLCC and LCC) Pinouts



16491C-6

LOGIC DIAGRAM (continued) SKINNYDIP (PLCC and LCC) Pinouts



16491C-6 (concluded)



Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied –55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage0.5 V to Vcc + 0.5 V
DC Output or I/O
Pin Voltage0.5 V to Vcc + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current
$(T_A = 0^{\circ}C \text{ to } 75^{\circ}C)$ 100 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Vон	Output HIGH Voltage	IOH = -3.2 mA VIN = VIH or VIL VCC = Min	2.4		>
Vol	Output LOW Voltage	IOL = 24 mA VIN = VIH or VIL VCC = Min		0.5	V
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0		٧
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	٧
IIH	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)		10	μΑ
hL	Input LOW Leakage Current	VIN = 0 V, Vcc = Max (Note 2)		-100	μΑ
lozн	Off-State Output Leakage Current HIGH	Vout = 5.25 V, Vcc = Max Vin = Vih or Vil (Note 2)		10	μА
lozı	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max Vin = Vih or Vil (Note 2)		-100	μА
Isc	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30	-150	mA
lcc (Static)	Supply Current	Outputs Open (lout = 0 mA), Vin = 0 V Vcc = Max		125	mA

- 1. These are absolute values with respect to device ground all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and IOZL (or IIH and IOZH).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

 Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Descriptions	Test Condition	าร	Тур	Unit
Cin	Input Capacitance	VIN = 2.0 V	Vcc = 5.0 V, TA = 25°C,	5	pF
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

Note:

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter Symbol	Parameter Descri	Min (Note 5)	Max	Unit		
tPD	Input or Feedback	to Combinatorial Output		1	5	ns
ts	Setup Time from In	put or Feedback to Clock		3		ns
tH	Hold Time			0		ns
tco	Clock to Output		_	1	4	ns
tskewr	Skew Between Reg	ew Between Registered Outputs (Note 4)			1	ns
twL	a	LOW		3		ns
twH	Clock Width	HIGH		3		ns
	Marrian	External Feedback	1/(ts+tco)	142.8		MHz
fmax	Maximum Frequency	Internal Feedback (fcnt)	•	166		MHz
	(Note 3)	No Feedback	1/(tw++twL)	166		MHz
tpzx	OE to Output Enable			1	6	ns
tpxz	OE to Output Disable			1	5	ns
tEA	Input to Output Enable Using Product Term Control			2	6	ns
ten	Input to Output Dis	able Using Product Term Contr	ol	2	5	ns

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- 4. Skew testing takes into account pattern and switching direction differences between outputs that have equal loading.
- Output delay minimums for tpD tcO tpZX tpXZ tpAZ teA and teR are defined under best case conditions. Future process
 improvements may alter these values therefore, minimum values are recommended for simulation purposes only.

These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with
Respect to Ground0.5 V to +7.0 V
DC Input Voltage -0.5 V to Vcc + 0.5 V
DC Output or I/O
Pin Voltage −0.5 V to Vcc + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current
(T _A = 0°C to 75°C)

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices	
Temperature (T _A) Operating	
in Free Air	0°C to 75°C
Supply Voltage (Vcc) with	
Respect to Ground +4.75	V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Vон	Output HIGH Voltage	IOH = -3.2 mA V _{IN} = V _{IH} or V _{IL} V _{CC} ≈ Min	2.4		V
V _{OL}	Output LOW Voltage	IOL = 24 mA VIN = VIH or VIL VCC = Min		0,5	٧
VIH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)			٧
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	٧
fін	Input HIGH Leakage Current	Vin = 5.25 V, Vcc = Max (Note 2)		10	μА
liL	Input LOW Leakage Current	V _{IN} ≈ 0 V, V _{CC} ≈ Max (Note 2)		-100	μΑ
ЮZН	Off-State Output Leakage Current HIGH	V _{OUT} = 5.25 V, V _{CC} = Max V _{IN} ≈ V _{IH} or V _{IL} (Note 2)		10	μА
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max Vin = ViH or ViL (Note 2)		-100	μА
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = Max (Note 3)	-30	-150	mA
lcc (Dynamic)	Supply Current	Outputs Open (IOUT = 0 mA) VCC = Max, f = 25 MHz		115	mA

- 1. These are absolute values with respect to device ground all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and IOZL (or IIH and IOZH).
- Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
 Vour= 0.5 V has been chosen to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Descriptions	Test Condition	ons	Тур	Unit
CIN	Input Capacitance	VIN = 2.0V	Vcc = 5.0 V, TA = 25°C,	5	pF
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

Note:

 These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter Symbol	Parameter Descrip	Min	Max	Unit		
tPD	Input or Feedback to	Combinatorial Output	8 Outputs Switching	3	7.5	ns
			1 Output Switching	3	7	ns
ts	Setup Time from Inc	out or Feedback to Clock		5		ns
tн	Hold Time			0		ns
tco	Clock to Output			1	5	ns
tskewr	Skew Between Reg	istered Outputs (Note 4)	ered Outputs (Note 4)			ns
twL	Clock Width LOW HIGH			4		ns
twn				4		ns
	Maximum	External Feedback	1/(ts+tco)	100		MHz
fMAX	Frequency	Internal Feedback (fcnt)	125		MHz
	(Note 3)	No Feedback	1/(tw++twL)	125		MHz
tPZX	OE to Output Enable	OE to Output Enable			6	ns
tpxz	OE to Output Disable			1	6	ns
tEA	Input to Output Enable Using Product Term Control			3	9	ns
ter	Input to Output Disa	ble Using Product Term Conf	trol	3	9	ns

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- 4. Skew testing takes into account pattern and switching direction differences between outputs that have equal loading.
- Output delay minimums for t_{PD} t_{CQ} t_{PZX} t_{PXZ} t_{EA} and t_{ER} are defined under best case conditions. Future process improvements may alter these values therefore, minimum values are recommended for simulation purposes only.



Storage Temperature -65°C to +150°C

Ambient Temperature
with Power Applied -55°C to +125°C

Supply Voltage with
Respect to Ground -0.5 V to +7.0 V

DC Input Voltage -0.5 V to Vcc + 0.5 V

DC Output or I/O
Pin Voltage -0.5 V to Vcc + 0.5 V

Static Discharge Voltage 2001 V

Latchup Current

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

 $(T_A = 0^{\circ}C \text{ to } 75^{\circ}C) \dots 100 \text{ mA}$

OPERATING RANGES

Commercial (C) Devices

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Voн	Output HIGH Voltage IOH = -3.2 mA VIN = VIH or VIL VCC = Min		2.4		>
Vol	Output LOW Voltage	IOL = 24 mA VIN = VIH or VIL VCC = Min		0.5	>
VIH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0		>
ViL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	>
Тін	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)		10	μΑ
lıL	Input LOW Leakage Current	VIN = 0 V, VCC = Max (Note 2)		-100	μΑ
lozн	Off-State Output Leakage Current HIGH	Vout = 5.25 V, Vcc = Max V _{IN} ≈ V _{IH} or V _{IL} (Note 2)		10	μА
lozi	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max Vin = ViH or ViL (Note 2)		-100	μΑ
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = Max (Note 3)	-30	-150	mA
lcc (Dynamic)	Supply Current	Outputs Open (I _{OUT} = 0 mA) VCC = Max, f = 25 MHz			mA

- 1. These are absolute values with respect to device ground all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and IOZL (or IIH and IOZH).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vout= 0.5 V has been chosen to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Description	Test Conditio	ns	Тур	Unit
Cin	Input Capacitance	VIN = 2.0 V	Vcc = 5.0 V, TA = 25°C,	5	pF
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

Note:

 These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter Symbol	Parameter Descrip	ption		Min (Note 4)	Max	Unit
tPD	Input or Feedback	to Combinatorial Output		3	10	ns
ts	Setup Time from In	put or Feedback to Cloc	k	7.5		ns
tH	Hold Time			0		ns
tco	Clock to Output				7.5	ns
twL	Clock Width	LOW	LOW			ns
twH	CIOCK WIGHT	HIGH	HIGH			ns
	Maximum	External Feedbac	k 1/(ts+tco)	66.7		MHz
fmax	Frequency	Internal Feedback	(fcnt)	71.4		MHz
	(Note 3)	No Feedback	1/(tw++twL)	83.3		MHz
tpzx	OE to Output Enab	le		2	10	ns
tpxz	OE to Output Disable		2	10	ns	
tEA	Input to Output Enable Using Product Term Control		3	10	ns	
tER	Input to Output Disable Using Product Term Control		3	10	ns	

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- Output delay minimums for ten too terx texx texx and ten are defined under best case conditions. Future process
 improvements may after these values therefore, minimum values are recommended for simulation purposes only.



Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied –55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage0.5 V to Vcc + 0.5 V
DC Output or I/O
Pin Voltage −0.5 V to Vcc + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

 $(T_A = 0^{\circ}C \text{ to } 75^{\circ}C) \dots 100 \text{ mA}$

OPERATING RANGES

Commercial (C) Devices	
Temperature (T _A) Operating	
in Free Air	0°C to 75°C
Supply Voltage (Vcc) with	
Respect to Ground +4.75	V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Vон	Output HIGH Voltage	IOH = −3.2 mA VIN ≈ VIH or VIL VCC = Min	2.4		>
Vol	Output LOW Voltage	IOL = 24 mA VIN = VIH or VIL VCC = Min		0.5	٧
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0		٧
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	٧
lн	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)		10	μΑ
lıL	Input LOW Leakage Current	V _{IN} = 0 V, V _{CC} = Max (Note 2)		-100	μ A
lozн	Off-State Output Leakage Current HIGH	Vout = 5.25 V, Vcc = Max Vin = ViH or ViL (Note 2)		10	μА
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max Vin = ViH or ViL (Note 2)		-100	μА
Isc	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30	-150	mA
lcc (Dynamic)	Supply Current	Outputs Open (Iout = 0 mA) Vcc = Max, f = 15 MHz (Note 4)		55	mA

- 1. These are absolute values with respect to device ground all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL}(or I_{IH} and I_{OZH}).
- Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
 VOUT= 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. This parameter is guaranteed worst case under test conditions. Refer to the ICCvs. frequency graph for typical measurements.

Parameter Symbol	Parameter Description	Test Conditio	ns	Тур	Unit
Cin	Input Capacitance	VIN = 2.0 V	VCC = 5.0 V, TA = 25°C,	5	pF
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

Note:

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter Symbol	Parameter Descri	ption		Min (Note 4)	Max	Unit
tPD	Input or Feedback	to Combinatorial Output		3	10	ns
ts	Setup Time from In	put or Feedback to Clock		7.5		ns
tн	Hold Time		_	0		ns
tco	Clock to Output			3	7.5	ns
twL	Clock Width	LOW		6		ns
twn	Clock Width	HIGH	HIGH			ns
	Maximum	External Feedback	1/(ts+tco)	66.7		MHz
fMAX	Frequency	Internal Feedback	(fCNT)	71.4		MHz
	(Note 3)	No Feedback	1/(tw++twL)	83.3		MHz
tpzx	OE to Output Enab	ole		2	10	ns
tpxz	OE to Output Disable		2	10	ns	
tEA	Input to Output Enable Using Product Term Control		3	10	ns	
t ER	Input to Output Disable Using Product Term Control		3	10	ns	

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- 4. Output delay minimums for ten ton ton ten ten ton ten ten are defined under best case conditions. Future process improvements may alter these values therefore, minimum values are recommended for simulation purposes only.

^{1.} These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

Storage Temperature ... -65°C to +150°C

Ambient Temperature
with Power Applied ... -55°C to +125°C

Supply Voltage with
Respect to Ground ... -0.5 V to +7.0 V

DC Input Voltage ... -0.5 V to Vcc + 0.5 V

DC Output or
I/O Pin Voltage ... -0.5 V to Vcc + 0.5 V

Static Discharge Voltage ... 2001 V

Latchup Current

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

 $(T_A = 0^{\circ}C \text{ to } +75^{\circ}C) \dots 100 \text{ mA}$

OPERATING RANGES

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions		Min	Мах	Unit
Vон	Output HIGH Voltage	IOH = -3.2 mA VIN = VIH or VIL VCC = Min	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1			>
Vol	Output LOW Voltage	IOL = 24 mA VIN = VIH or VIL VCC = Min			0.5	V
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)		2.0		٧
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)				٧
lin .	Input HIGH Leakage Current	VIN = 5.25 V, VCC = Max (Note 2)			10	μА
lıL	Input LOW Leakage Current	VIN = 0 V, VCC = Max (Note 2)		_	-100	μA
lozн	Off-State Output Leakage Current HIGH	Vout = 5.25 V, Vcc = Max Vin = ViH or ViL (Note 2)				μА
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max Vin = Vih or Vil. (Note 2)			-100	μА
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = Max (Note 3)		-30	-150	mA
lcc	Supply Current	Outputs Open (Iout = 0 mA) Vcc = Max, f = 15 MHz	H Q		90 55	mA

- 1. These are absolute values with respect to device ground all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of I/L and IOZL (or I/H and IOZH).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vout= 0.5 V has been chosen to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
CIN	Input Capacitance	VIN = 2.0 V VC	C = 5.0 V, TA = 25°C,	5	pF
Cout	Output Capacitance	Vour = 2.0 V f =	1 MHz	8	pF

Note:

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter				-19	5	-25	5	
Symbol	Parameter Descri	Parameter Description		Min	Max	Min	Max	Unit
tPD	Input or Feedback	to Combinatorial Outp	ut		15		25	ns
ts	Setup Time from Ir	nput or Feedback to Cl	ock	12		15		ns
tн	Hold Time			0		0		ns
tco	Clock to Output				10		12	ns
tw∟	OL LANGUA	LOW		8		12		ns
twn	Clock Width	HIGH	HIGH			12		ns
	Maximum	External Feedbac	ck 1/(ts+tco)	45.5		37		MHz
fmax	Frequency	Internal Feedbac	ck (font)	50		40		MHz
	(Note 3)	No Feedback	1/(tw++twL)	62.5		41.6		MHz
tpzx	OE to Output Enab	ole			15		20	ns
texz	OE to Output Disa	tput Disable			15		20	ns
tEA	Input to Output En	Output Enable Using Product Term Control			15		25	ns
ter	Input to Output Dis	sable Using Product Te	erm Control		15		25	ns

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.

These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Storage Temperature $\ \dots \ -65^{\circ}\text{C}$ to $+150^{\circ}\text{C}$
Ambient Temperature with Power Applied
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage -0.5 V to $\text{Vcc} + 0.5 \text{ V}$
DC Output or
I/O Pin Voltage0.5 V to Vcc + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

 $(T_A = -40^{\circ}C \text{ to } +85^{\circ}C) \dots 100 \text{ mA}$

OPERATING RANGES

Industrial (I) Devices

Supply Voltage (Vcc)

with Respect to Ground +4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over INDUSTRIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions		Min	Max	Unit
Vон	Output HIGH Voltage	IOH = -3.2 mA VIN = VIH or VIL VCC = Min		2.4		V
Vol	Output LOW Voltage	IOL = 24 mA VIN = VIH or VIL VCC = Min				٧
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)				٧
VıL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	٧
lн	Input HIGH Leakage Current	V _{IN} = 5.5 V, V _{CC} = Max (Note 2)			10	μА
l _{IL}	Input LOW Leakage Current	V _{IN} = 0 V, V _{CC} = Max (Note 2)			-100	μΑ
lozh	Off-State Output Leakage Current HIGH	Vout = 5.5 V, Vcc = Max V _{IN} = V _{IH} or V _{IL} (Note 2)	1		10	μА
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max V _{IN} = V _{IH} or V _{IL} (Note 2)		-100	μА	
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = Max (Note 3) -30		-30	-150	mA
lcc	Supply Current	Outputs Open (IouT = 0 mA) Vcc = Max, f = 15 MHz Q		130 65	mA	

- 1. These are absolute values with respect to device ground all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and IOZL(or IIH and IOZH).
- Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
 VOUT= 0.5 V has been chosen to avoid test problems caused by tester ground degradation.



Parameter Symbol	Parameter Description	Test Condition	Test Conditions		
Cin	Input Capacitance	VIN = 2.0 V	VCC = 5.0 V, TA = 25°C,	5	pF
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

Note:

SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2)

D	T			-1	5	-2	0	-2	25	
Parameter Symbol	Parameter De	Parameter Description			Max	Min	Max	Min	Max	Unit
tPD	Input or Feedb	pack to Combinatorial C	Dutput		15		20		25	ns
ts	Setup Time fro	om Input or Feedback t	o Clock	12		13		15		ns
tн	Hold Time			0		0		0		ns
tco	Clock to Outpu	ut	t		10		11		12	ns
twL	Clock Width	LOW	LOW			10		12		ns
twn	Clock Width	HIGH	HIGH			10		12		ns
	Maximum	External Feedback	1/(ts+tco)	45.5		41.6		37		MHz
fmax	Frequency	Internal Feedback (fo	CNT)	50		45.4		40		MHz
	(Note 3)	No Feedback	1/(twH+twL)	62.5		50.0		41.6		MHz
tpzx	OE to Output	OE to Output Enable			15		18		20	ns
tpxz	OE to Output	tput Disable			15		18		20	ns
tEA	Input to Outpu	Enable Using Product Term Control			15		18		20	ns
tER	Input to Outpu	t Disable Using Produc	t Term Control		15		18		20	ns

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.

These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied –55°C to +125°C
Supply Voltage with Respect to Ground ~0.5 V to +7.0 V
DC Input Voltage0.5 V to Vcc + 1.0 V
DC Output or I/O
Pin Voltage0.5 V to Vcc + 1.0 V
Static Discharge Voltage 2001 V
Latchup Current
$(T_c = -55^{\circ}C \text{ to } +125^{\circ}C)$

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ. Absolute Maximum Ratings are for system design reference; parameters given are not tested.

OPERATING RANGES

Military (M) Devices (Note 1)

Operating Case

Temperature (Tc) -55°C to +125°C

Supply Voltage (Vcc)

with Respect to Ground +4.5 V to +5.5 V

Note:

 Military products are tested at Tc = +25°C, +125°C and -55°C, per MIL-STD-883.

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over MILITARY operating ranges unless otherwise specified (Note 2)

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Vон	Output HIGH Voltage	IOH = -2.0 mA VIN = VIH or VIL Vcc = Min	2.4		>
Vol	Output LOW Voltage	IoL = 12 mA VIN = VIH or VIL VCC = Min		0.5	V
VIH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 3)	2.0		>
ViL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 3)		0.8	>
lin	Input HIGH Leakage Current	VIN = 5.5 V, VCC = Max (Note 4)		10	μΑ
hг	Input LOW Leakage Current	VIN = 0 V, VCC = Max (Note 4)		-100	μА
lozн	Off-State Output Leakage Current HIGH	Vout = 5.5 V, Vcc = Max Vin = ViH or ViL (Note 4)		10	μА
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max Vin = ViH or ViL (Note 4)		-100	μА
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = 5.0 V, Ta = 25°C (Note 5)	-30	-150	mA
lcc	Supply Current (Dynamic)	Outputs Open (Iout = 0 mA) Vcc = Max, f = 25 MHz		130	mA

- 2. For APL products, Group A, Subgroups 1, 2 and 3 are tested per MIL-STD-833, Method 5005, unless otherwise noted.
- 3. VIL and VIHare input conditions of output tests and are not themselves directly tested. VIL and VIHare absolute voltages with respect to device ground and include all overshoots due to system and/or tester noise. Do not attempt to test these values without suitable equipment.
- 4. I/O pin leakage is the worst case of IIL and IOZL(or IIH and IOZH).
- 5. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vour= 0.5 V has been chosen to avoid test problems caused by tester ground degradation. This parameter is not 100% tested, but is evaluated at initial characterization and at any time the design is modified where Isc may be affected.

Parameter Symbol	Parameter Description	Test Condition	Тур	Unit	
Cin	Input Capacitance	VIN = 2.0 V	Vcc = 5.0 V, TA = 25°C,	8	pF
Соит	Output Capacitance	Vout ≈ 2.0 V	f = 1 MHz	8	pF

Note:

SWITCHING CHARACTERISTICS over MILITARY operating ranges (Note 2)

	<u> </u>				-15	
Parameter Symbol	Parameter Descrip	otion		Min (Note !	5) Max	Unit
tpD	Input or Feedback t	to Combinatorial Output		3	15	ns
ts	Setup Time from In	put or Feedback to Cloc	k	12		ns
tH	Hold Time			0		ns
tco	Clock to Output		3	12	ns	
twL	Charl Marin	LOW		10		ns
twн	Clock Width	HIGH		10		ns
	Maximum	External Feedbac	k 1/(ts+tco)	41.6		MHz
,fmax	Frequency	Internal Feedback	(font)	45.5		MHz
	(Note 3)	No Feedback	1/(tw++twL)	50.0		MHz
tpzx	OE to Output Enab	le		3	15	ns
texz	OE to Output Disable		3	15	ns	
tea .	Input to Output Enable Using Product Term Control (Note 4)		3	15	ns	
ter	Input to Output Disable Using Product Term Control (Note 4)			3	15	ns

- See Switching Test Circuit for test conditions. For APL Products, Group A, Subgroups 9, 10, and 11 are tested per MIL-STD-883, Method 5005, unless otherwise noted.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- 4. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where these parameters may be affected.
- 5. Output delay minimums for tpD, tcQ, tpZX tpXZ tpAZ teA, and teA are defined under best case conditions. Future process improvements may alter these values therefore, minimum values are recommended for simulation purposes only.

These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Storage Temperature65°C to +150°	C
Ambient Temperature with Power Applied~55°C to +125°	C
Supply Voltage with Respect to Ground0.5 V to +7.0	٧
DC Input Voltage0.5 V to Vcc + 0.5	٧
DC Output or I/O	
Pin Voltage −0.5 V to Vcc + 0.5	٧
Static Discharge Voltage 2001	٧
Latchup Current	
$(T_C = -55^{\circ}C \text{ to } +125^{\circ}C)$ 100 m	ıA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ. Absolute Maximum Ratings are for system design reference; parameters given are not tested.

OPERATING RANGES

Military (M) Devices (Note 1)

-55° C, per MIL-STD-883.

Note:1. Military products are tested at $T_C = +25^{\circ}C$, $+125^{\circ}C$ and

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over MILITARY operating ranges unless otherwise specified (Note 2)

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Vон	Output HIGH Voltage	IOH = -2.0 mA VIN = VIH or VIL VCC = Min	2.4		>
VOL	Output LOW Voltage	IOL = 12 mA VIN = VIH or VIL VCC = Min		0.5	٧
VIH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 3)	2.0		>
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 3)		0.8	V
łін	Input HIGH Leakage Current	V _{IN} = 5.5 V, V _{CC} = Max (Note 4)		10	μΑ
lμ	Input LOW Leakage Current	VIN = 0 V, VCC = Max (Note 4)		-100	μΑ
lozн	Off-State Output Leakage Current HIGH	Vout = 5.5 V, Vcc ≈ Max V _{IN} = V _{IH} or V _{IL} (Note 4)		10	μА
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max VIN = VIH or VIL (Note 4)		-100	μА
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = 5.0 V, Ta = 25°C (Note 5)	-30	-150	mA
lcc	Supply Current (Dynamic)	Outputs Open (Iout = 0 mA) Vcc = Max, f = 25 MHz		130	mA

- 2. For APL products, Group A, Subgroups 1, 2 and 3 are tested per MIL-STD-833, Method 5005, unless otherwise noted.
- 3. VIL and VIHare input conditions of output tests and are not themselves directly tested. VIL and VIHare absolute voltages with respect to device ground and include all overshoots due to system and/or tester noise. Do not attempt to test these values without suitable equipment.
- 4. I/O pin leakage is the worst case of IIL and IOZL(or IIH and IOZH).
- 5. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
 VOUT= 0.5 V has been chosen to avoid test problems caused by tester ground degradation. This parameter is not 100% tested, but is evaluated at initial characterization and at any time the design is modified where Isc may be affected.

Parameter Symbol	Parameter Description	Test Condition	Test Conditions		
CIN	Input Capacitance	VIN = 2.0 V	VCC = 5.0 V, TA = 25°C,	8	pF
Соит	Output Capacitance	Vour = 2.0 V	f ≈ 1 MHz	8	pF

Note:

 These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

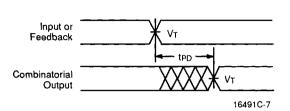
SWITCHING CHARACTERISTICS over MILITARY operating ranges (Note 2)

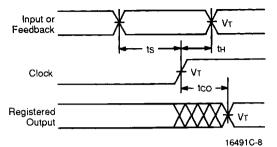
Parameter			-2	:0	-25			
Symbol	Parameter Description	on		Min	Max	Min	Max	Unit
tPD	Input or Feedback to (Combinatorial Output			20		25	ns
ts	Setup Time from Input	or Feedback to Cloc	k	15		20		ns
tH	Hold Time (Note 5)			0		0		ns
tco	Clock to Output			15		20	ns	
twL	Clarate Militalia	LOW		12		15		ns
twH	Clock Width	HIGH		12		15		ns
-	Maximum	External Feedback	1/(ts+tco)	33.3		25		MHz
fmax	Frequency	Internal Feedback (fcnt)	35.7		26.3		MHz
	(Note 3)	No Feedback	1/(twH+twL)	41.7		33.3		MHz
tPZX	OE to Output Enable	(Note 3)		<u> </u>	18		20	ns
tPXZ	OE to Output Disable	OE to Output Disable (Note 3)			18		20	ns
tEA	Input to Output Enable Term Control (Note 3)	Using Product	<u></u>		20		25	ns
ten	Input to Output Disable Term Control (Note 3)	Using Product			20		25	ns

- See Switching Test Circuit for test conditions. For APL Products, Group A, Subgroups 9, 10, and 11 are tested per MIL-STD-883, Method 5005, unless otherwise noted.
- These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where these parameters may be affected.



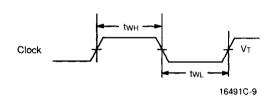
SWITCHING WAVEFORMS

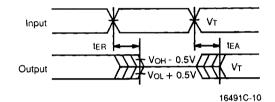




Combinatorial Output

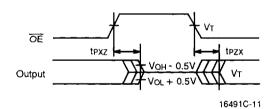
Registered Output





Clock Width

Input to Output Disable/Enable



OE to Output Disable/Enable

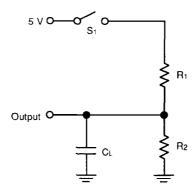
- 1. $V_T = 1.5 V$
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns 5 ns typical.

KEY TO SWITCHING WAVEFORMS

WAVEFORM	INPUTS	OUTPUTS
	Must be Steady	Will be Steady
	May Change from H to L	Will be Changing from H to L
	May Change from L to H	Will be Changing from L to H
	Don't Care, Any Change Permitted	Changing, State Unknown
>>	Does Not Apply	Center Line is High- Impedance "Off" State

KS000010-PAL

SWITCHING TEST CIRCUIT

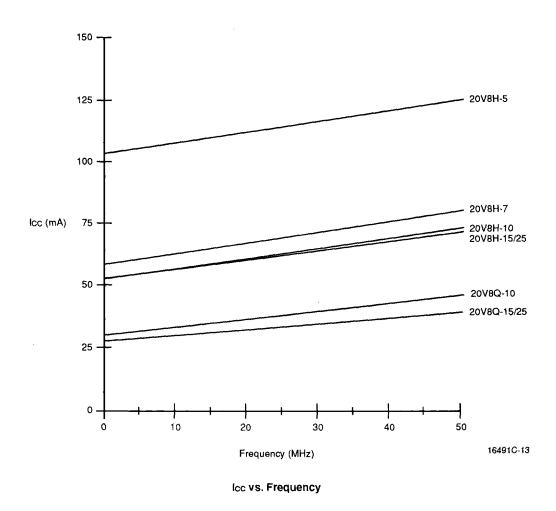


Switching Test Circuit

16491C-12

			Comm	commercial Military Meass		Measured	
Specification	St	CL	R ₁	R ₂	R ₁	R ₂	Output Value
tPD, tCO	Closed	50 pF					1.5 V
tPZX, tEA	$Z \rightarrow H$: Open $Z \rightarrow L$: Closed	50 pF	200 Ω	390 Ω H-5:	390 Ω	750 Ω	1.5 V
tpxz, ter	H → Z: Open L → Z: Closed	5 pF		200 Ω			H → Z: VoH - 0.5 V L → Z: VoL + 0.5 V

TYPICAL Icc CHARACTERISTICS Vcc = 5.0 V, T_A = 25°C



The selected "typical" pattern utilized 50% of the device resources. Half of the macrocells were programmed as registered, and the other half were programmed as combinatorial. Half of the available product terms were used for each macrocell. On any vector, half of the outputs were switching.

By utilizing 50% of the device, a midpoint is defined for I_{CC} From this midpoint, a designer may scale the I_{CC} graphs up or down to estimate the I_{CC} requirements for a particular design.

ENDURANCE CHARACTERISTICS

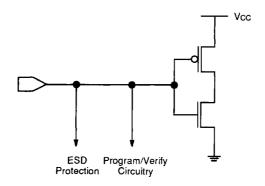
The PALCE20V8 is manufactured using AMD's advanced electrically erasable process. This technology

uses an EE cell to replace the fuse link used in bipolar parts. As a result, the device can be erased and reprogrammed—a feature which allows 100% testing at the factory.

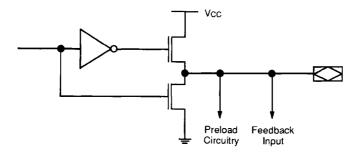
Endurance Characteristics

Symbol	Parameter	Test Conditions	Min	Unit
		Max Storage Temperature	10	Years
tDR	Min Pattern Data Retention Time	Max Operating Temperature	20	Years
N	Min Reprogramming Cycles	Normal Programming Conditions	100	Cycles

INPUT/OUTPUT EQUIVALENT SCHEMATICS



Typical Input



Typical Output

16491C-14

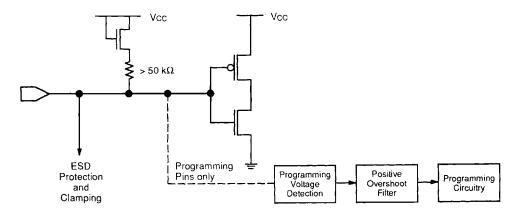
ROBUSTNESS FEATURES

The PALCE20V8X-X/5 have some unique features that make them extremely robust, especially when operating in high-speed design environments. Pull-up resistors on inputs and I/O pins cause unconnected pins to default to a known state. Input clamping circuitry limits negative overshoot, eliminating the possibility of false clocking

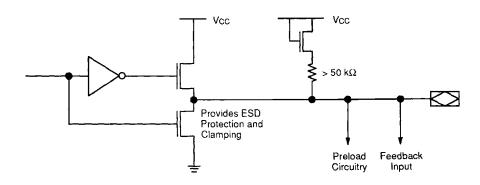
caused by subsequent ringing. A special noise filter makes the programming circuitry completely insensitive to any positive overshoot that has a pulse width of less than about 100 ns for the /5 versions.

Selected /4 devices are also being retrofitted with these robustness features. See the chart below for device listings.

INPUT/OUTPUT EQUIVALENT SCHEMATICS FOR /5 VERSION AND SELECTED /4 VERSIONS*



Typical Input



Typical Output

16491C-15

Device	Rev Letter
PALCE20V8H-10	К
PALCE20V8H-15	K, J
PALCE20V8Q-15	J
PALCE20V8H-25	J
PALCE20V8Q-25	J

Topside Marking:

AMD CMOS PLD's are marked on top of the package in the following manner:

PALCEXXXX

Datecode (3 numbers) Lot ID (4 characters)- -(Rev Letter)

The Lot ID and Rev Letter are separated by two spaces.

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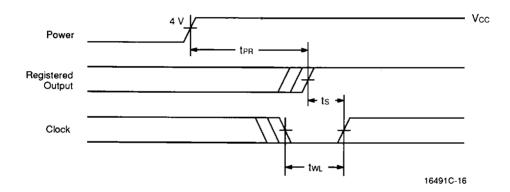
POWER-UP RESET

The PALCE20V8 has been designed with the capability to reset during system power-up. Following power-up, all flip-flops will be reset to LOW. The output state will be HIGH independent of the logic polarity. This feature provides extra flexibility to the designer and is especially valuable in simplifying state machine initialization. A timing diagram and parameter table are shown below.

Due to the synchronous operation of the power-up reset and the wide range of ways Vcc can rise to its steady state, two conditions are required to insure a valid power-up reset. These conditions are:

- The Vcc rise must be monotonic.
- Following reset, the clock input must not be driven from LOW to HIGH until all applicable input and feedback setup times are met.

Parameter Symbol	Parameter Description	Min	Max	Unit	
tpa	Power-Up Reset Time		1000	ns	
ts	Input or Feedback Setup Time	s	See Switching Characteristics		
twL	Clock Width LOW				



Power-Up Reset Waveforms



TYPICAL THERMAL CHARACTERISTICS

/4 Devices (PALCE20V8H-10/4)

Measured at 25°C ambient. These parameters are not tested.

Parameter		Тур			
Symbol	Parameter Description	SKINNYDIP	PLCC	Unit	
θjc	Thermal impedance, junction to case		19	19	°C/W
θja	Thermal impedance, junction to ambient		73	55	°C/W
θ _{jma} Thermal impedance, junct ambient with air flow	Thermal impedance, junction to	200 Ifpm air	61	45	°C/W
	ambient with air flow	400 lfpm air	53	41	°C/W
		600 Ifpm air	50	38	°C/W
		800 lfpm air	47	36	°C/W

/5 Devices (PALCE20V8H-7/5)

Measured at 25°C ambient. These parameters are not tested.

Parameter		Тур			
Symbol	Parameter Description	SKINNYDIP	PLCC	Unit	
θjc	Thermal impedance, junction to case		18	16	•c/w
θја	Thermal impedance, junction to ambient		69	51	°C/W
	Thermal impedance, junction to ambient with air flow	200 lfpm air	60	42	∘C/W
		400 lfpm air	54	37	°C/W
		600 Ifpm air	50	36	°C/W
		800 lfpm air	×	X	°C/W

Plastic θjc Considerations

The data listed for plastic θ ic are for reference only and are not recommended for use in calculating junction temperatures. The heat-flow paths in plastic-encapsulated devices are complex, making the θ ic measurement relative to a specific location on the package surface. Tests indicate this measurement reference point is directly below the die-attach area on the bottom center of the package. Furthermore, θ ic tests on packages are performed in a constant-temperature bath, keeping the package surface at a constant temperature. Therefore, the measurements can only be used in a similar environment.



DATA SHEET REVISION SUMMARY FOR PALCE20V8 Family

Title

Added H-15/25, Q-20/25 (Ind) to family

Ordering Information

Updated valid combinations table to include:

PALCE20V8H-15 PI,JI PALCE20V8H-25 PI,JI PALCE20V8Q-20 PI,JI PALCE20V8Q-25 PI,JI

Added Industrial Temperature Grade (-40°C to +85°C)

Changed footer to include H-15/25, Q-20/25 (Ind)

DC Characteristics

For PALCE20V8H-10/15/25, Q-10/15/25 (Com'l) and PALCE20V8H-15/20/25 (Mil)

Changed I_{IL} and I_{OZL} Max from -10 μA to -100 μA

For the PALCE20V8Q-10, Com'l added Note 4: This parameter is guaranteed worst case under test conditions. Refer to the lcc vs. frequency graph for typical measurements.

Icc vs. Frequency Curve

Added PALCE20V8Q-10